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Front Matter: Volume 10284

, "Front Matter: Volume 10284," Proc. SPIE 10284, Optoelectronic Interconnects and Packaging: A Critical Review, 1028401 (30 January 1996); doi: 10.1117/12.2285114

SPIE.

Event: Photonics West '96, 1996, San Jose, CA, United States

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Optoelectronic Interconnects and Packaging: A Critical Review, edited by Ray T. Chen,
Peter S. Guilfoyle, Proc. of SPIE Vol. 10284 (Vol. CR62), 1028401 · © (1996) 2017 SPIE
CCC code: 0277-786X/17/\$18 · doi: 10.1117/12.2285114

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Conference Chairs

Ray T. Chen, University of Texas/Austin
Peter S. Guilfoyle, OptiComp Corporation

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Preface

Optoelectronic interconnects and packaging are becoming increasingly important due to the requirement of high-speed, large-capacity transmission of information. Such a demand in many scenarios such as machine-to-machine and module-to-module interconnects can only be realized by employing optoelectronic technology.

In this critical review, we have invited 26 internationally known experts in this field to address such critical technical issues as vertical cavity surface emitting lasers, photodetectors, holograms and smart pixel arrays for both guided wave and free-space optoelectronic interconnects. Architecture-related subjects are also delineated to provide a global picture of future development. Several system demonstrations, including 500-MHz optical clock signal distribution for Cray Research's T-90 machine, ARPA-sponsored POINT and POLO programs, and the most recent developments on optoelectronic packaging are also detailed in this book.

We expect the engineers, scientists, and students in this field to find this book useful for their research.

Ray T. Chen
Peter S. Guilfoyle